



# TOIR-30a94cXAa

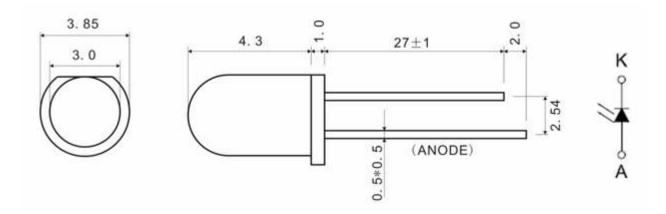
## **Lamp LED**

Part Number	Chip		Lens Color	
r art Number	Material	Source Color	Lens Color	
TOIR-30a94cXAa	AlGaAs	Infrared	Blue Transparent	

### **Features**

- I.C. compatible.
- Low power consumption.
- Compatible with wave soldering process.
- 3mm diameter package.
- Long life, stable and reliable.
- · RoHS compliant

### **Dimensions**



### Notes:

- 1. All dimensions are in millimeter.
- 2. Tolerance is ±0.25mm unless otherwise noted.

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## Absolute Maximum Rating @ Ta=25°C

Parameter	Maximum Rating	Unit	
Continuous Forward Current	100	mA	
Power Dissipation	75	mW	
Reverse Voltage	5	V	
Operating Temperature Range	-40°C to +80°C		
Storage Temperature Range	-40°C to +100°C		
Wave Soldering Profile For Lead-free Soldering	260°C for 5 Sec		

# Electrical / Optical Characteristic @ Ta=25°C

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Peak Wavelength	λр	-	940	-	nm	I <sub>F</sub> =50mA
Radiated Output Power	Po	13.9	-	53	mW/Sr	I <sub>F</sub> =50mA
Viewing Angle	2θ <sub>1/2</sub>	-	40	-	deg	I <sub>F</sub> =50mA
Spectral Line Half-Width	$\triangle \lambda$	-	50	-	nm	I <sub>F</sub> =50mA
Forward Voltage	$V_{F}$	1.1	-	1.5	V	I <sub>F</sub> =50mA
Reverse Current	I <sub>R</sub>	-	-	10	uA	V <sub>R</sub> =5V

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### **Bin Code List for Reference**

Radiant Intensity	Unit: mW/Sr @50mA		
Bin Code	Min	Max	
A21	13.9	17.3	
A22	17.3	21.7	
A23	21.7	27.1	
A24	27.1	33.9	
A25	33.9	42.4	
A26	42.4	53	

Tolerance of Luminous Intensity on each bin is ±15%

Forward Voltage		Unit:V@50mA
Bin Code	Min	Max
V1.1	1.1	1.3
V1.3	1.3	1.5

Tolerance for each Forward Voltage Bin is ±0.1V

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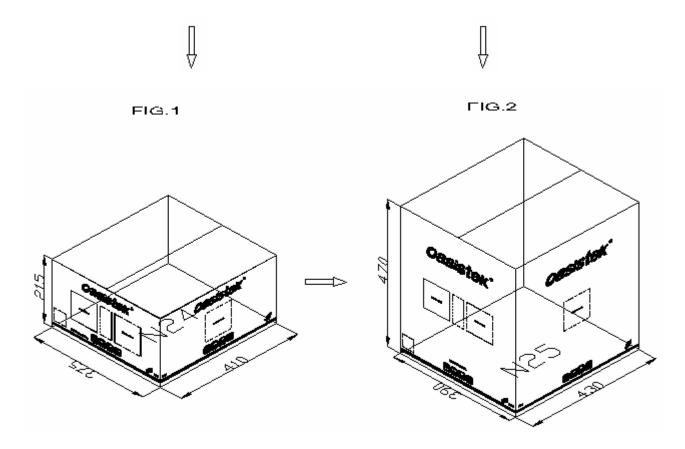




### **Package Description**







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# **Reliability Test Project**

Description	Item	Test criterion	Test condition	Test time	Qty	Fail Qty
Life test	Life test (Room temperature)	JIS7021:B4 Ta=25°ℂ±5°ℂ,IF=50mA		1000 Hrs	20	0
	High temperature store	JIS7021:B10 MIL-STD-202:210A MIL-STD-750:2031	Ta=85°ℂ±5°ℂ	1000 Hrs	20	0
	Low temperature store	JIS7021:B12	Ta= -35°∁±5°∁	1000 Hrs	20	0
Ambience test	High temperature/ humidity test	JIS7021:B11 MIL-STD-202:103D	Ta=85°C±5°C RH=85%	1000 Hrs	20	0
	Cold / Heat strike test	JIS7021::B4 MIL-STD-202:107D MIL-STD-750:1026	30min -10°C±5°C ←→85°C±5°C 5min 5min	50 Cycles	20	0
	Cold and heat cycle test	JIS7021:A3 MIL-STD-202:107D MIL-STD-705:105E	5min 5min 5min -35°C ~25°C ~85°C ~-35°C 30min 5min 30min 5min	50 Cycles	20	0

# **Judging criterion**

Item	Symbol	Experiment	Criteria		
item	Syrribor	condition	Min.	Max.	
Forward Voltage	VF	IF=50mA	-	Initial Datex1.1	
Reverse Current	IR	VR=5V	-	30μΑ	
Luminous Intensity	IV	IF=50mA	Initial Datex0.7	-	

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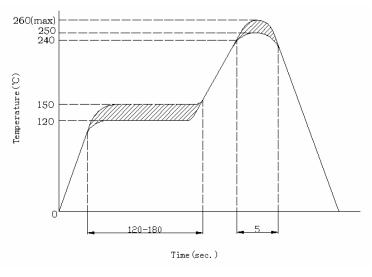


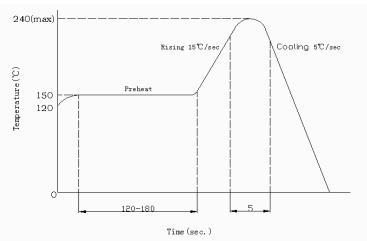
### **Cautions**

- LED bracket forming method :
  - 1. The pin of led can be bent where is at least 3mm out of led colloid.
  - 2. Must use fixture to deform the led bracket.
  - 3. Finishing the forming of led bracket must be before soldering.
  - 4. Guarantee the gap between two pin of led tallys with LED pads in PCB when forming.
- Manual soldering :

The tip temperature of soldering iron don't exceed 260°C; soldering time don't exceed 3s and soldering position must be 3mm out of led colloid.

Soldering temperature curve chart (figure A figure B):





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#### ESD countermeasure

Static electricity and high volt can damage led. The production whose Die material is InGaN must strictly required to prevent ESD, must put on static glove and static fillet. Soldering tool and the cover of device must connect the ground, soldering condition follows the related stating of production specification manual.

### Protecting countermeasure when over current

Need add the protecting resistor in circuit in order to avoid damaging led due to big current and voltage fluctuation.

#### LED installation method

- 1. Pay attention to the led polarity and avoid installation wrong. LED can't be close to euthermic component, work condition should tally with it's specification.
- 2. Don't install the LED under the condition of the led pin deformation.
- 3. The led bracket don't load any pressure when installing the led into PCB or fitting hole.
- 4. Must avoid any strike and force on led before the soldering temperature return to room temperature.

#### Storage time

1. LED can be stored for a year under the condition:

the temperature of  $5^{\circ}$ C  $\sim$ 35 $^{\circ}$ C and humidity of RH60%, These production must be re-inspected and tested before use if their storage time exceed a year.

2. If LED is exposed in air for a week under the condition:

the temperature of  $5^{\circ}$ C $\sim$ 35 $^{\circ}$ C, humidity of RH60%, must place the led in the ambience of  $65^{\circ}$ C $\pm$ 5 $^{\circ}$ C for 24 hours and use it in 15 days for best.

### Cleaning

Be careful of some chemical results in the led colloid fades and damage when using chemical clean the LED such as chloroethylene, acetone etc. can use ethanol to wash or soak LED but the time don't exceed 3 minutes.

#### Kinked

The kinked tooling scrape easily the pin of LED, where the led bracket is rusting easily, especial expose it in moist air. To decrease the led bracket rust, suggest using plated tin led bracket.

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